

TN25 and TYNx25 Series

Tables 4: Electrical Characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions			Value	Unit
I _{GT}	V _D = 12 V R _L = 33 Ω		MIN.	4	mA
			MAX.	40	
V _{GT}			MAX.	1.3	V
V _{GD}	V _D = V _{DRM} R _L = 3.3 kΩ	T _j = 125°C	MIN.	0.2	V
I _H	I _T = 500 mA Gate open		MAX.	50	mA
I _L	I _G = 1.2 x I _{GT}		MAX.	90	mA
dV/dt	V _D = 67 % V _{DRM} Gate open	T _j = 125°C	MIN.	1000	V/μs
V _{TM}	I _{TM} = 50 A tp = 380 μs	T _j = 25°C	MAX.	1.6	V
V _{t0}	Threshold voltage	T _j = 125°C	MAX.	0.77	V
R _d	Dynamic resistance	T _j = 125°C	MAX.	14	mΩ
I _{DRM} I _{RRM}	V _{DRM} = V _{RRM}	T _j = 25°C	MAX.	5	μA
		T _j = 125°C		4	mA

Table 5: Thermal resistance

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case (DC)			1.0	$^\circ\text{C/W}$
$R_{th(j-a)}$	Junction to ambient (DC)	$S = 01\text{ cm}^2$	D ² PAK	45	$^\circ\text{C/W}$
			TO-220AB	60	

S = Copper surface under tab.

Figure 1: Maximum average power dissipation versus average on-state current

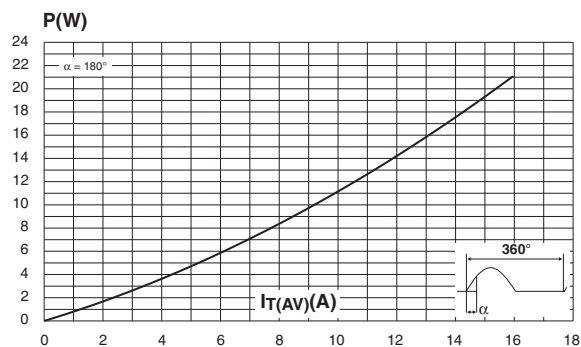


Figure 2: Average and D.C. on-state current versus case temperature

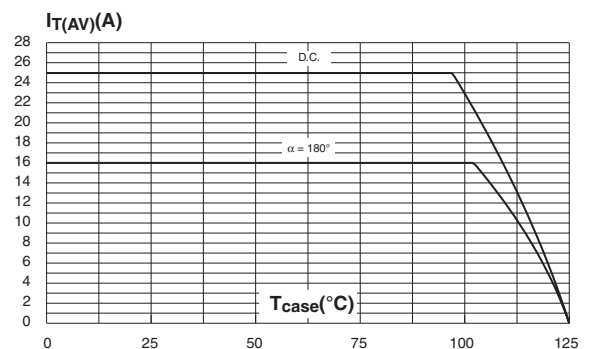


Figure 3: Average and D.C. on-state current versus ambient temperature (copper surface under tab: $S=1\text{cm}^2$) ($D^2\text{PAK}$)

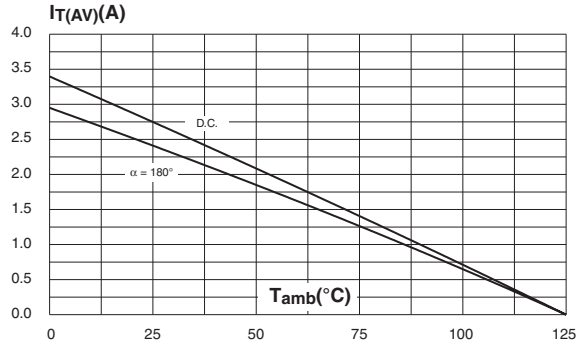


Figure 4: Relative variation of thermal impedance versus pulse duration

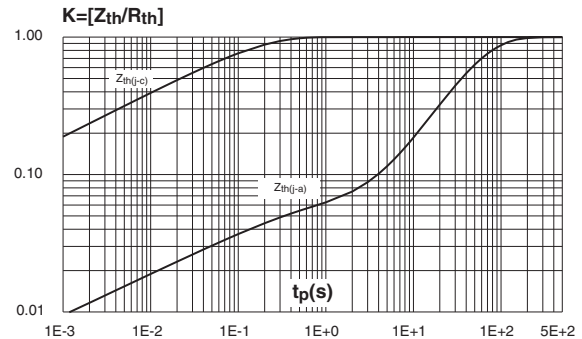


Figure 5: Relative variation of gate trigger current, holding current and latching current versus junction temperature

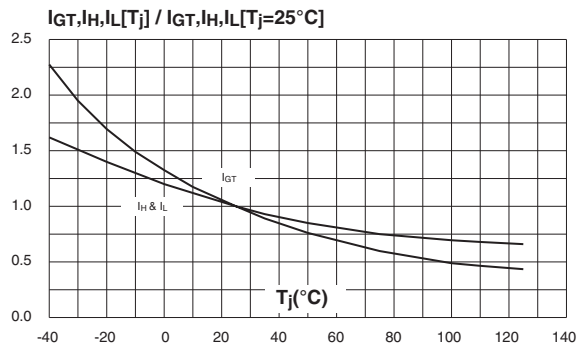


Figure 6: Surge peak on-state current versus number of cycles

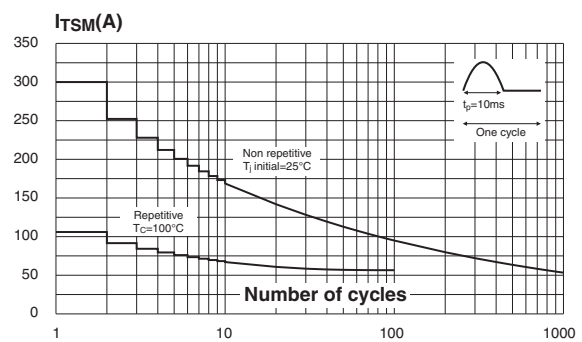


Figure 7: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding values of I^2t

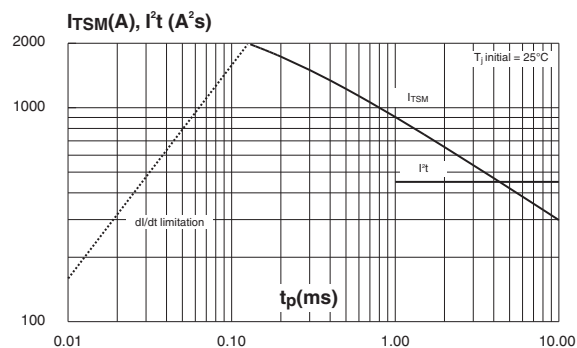
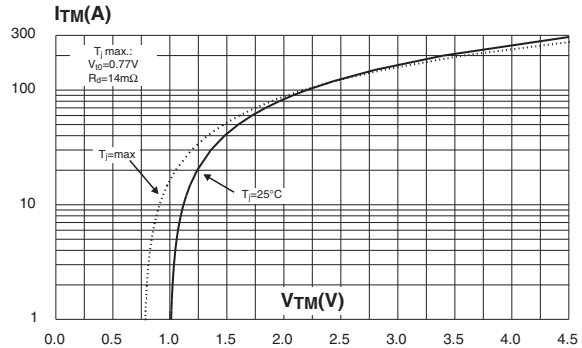


Figure 8: On-state characteristics (maximum values)



TN25 and TYNx25 Series

Figure 9: Thermal resistance junction to ambient versus copper surface under tab (epoxy printed circuit board FR4, copper thickness: 35μm) (D²PAK)

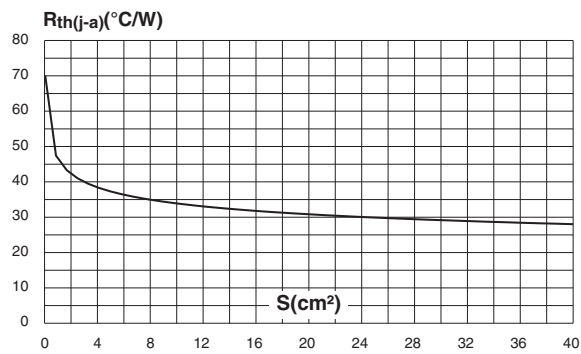


Figure 10: Ordering Information Scheme (TN25 series)

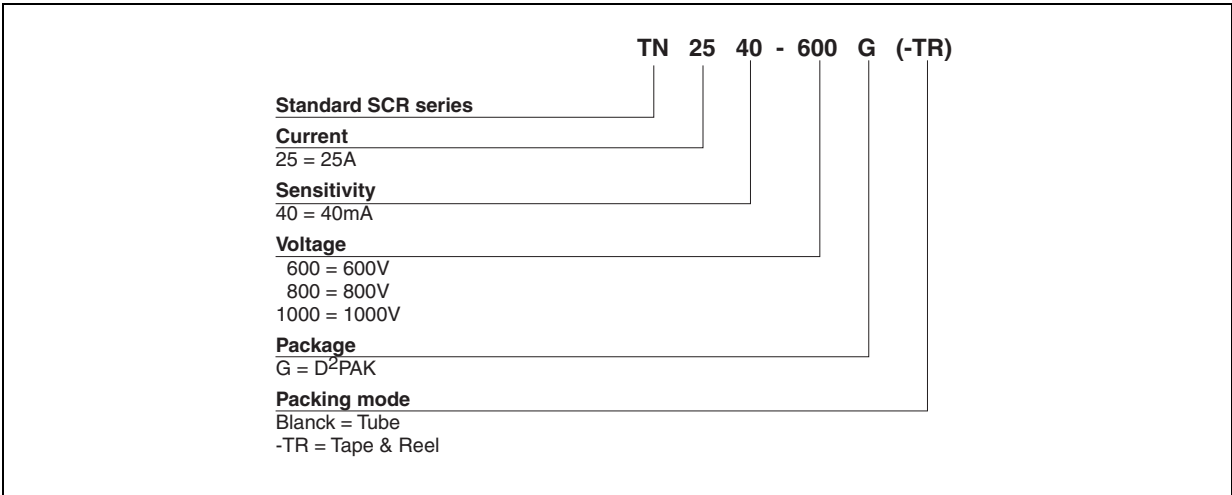


Figure 11: Ordering Information Scheme (TYN25 series)

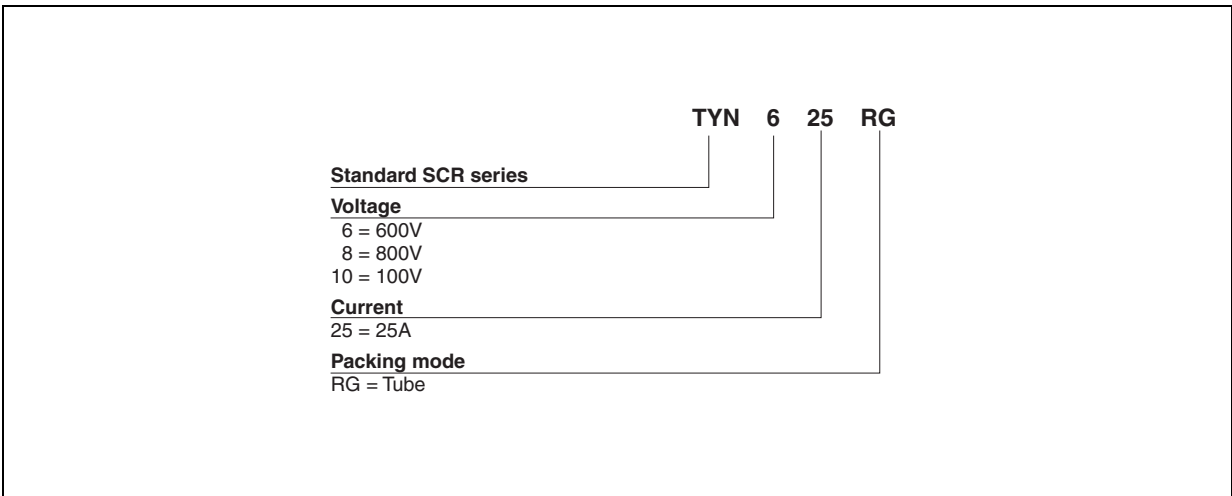


Table 6: Product Selector

Part Numbers	Voltage (xxx)			Sensitivity	Package
	600 V	800 V	1000 V		
TN2540-xxxG	X	X	X	40 mA	D ² PAK
TYNx25	X	X	X	40 mA	TO-220AB

Figure 12: D²PAK Package Mechanical Data

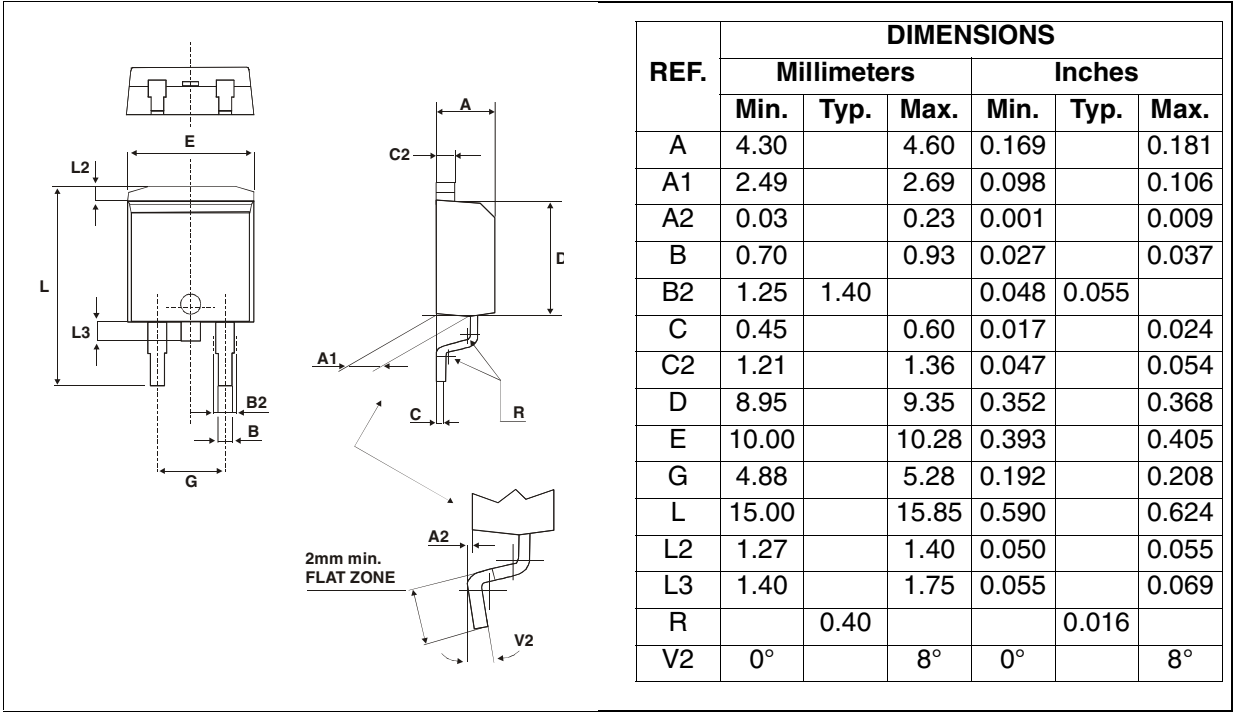


Figure 13: D²PAK Foot Print Dimensions
(in millimeters)

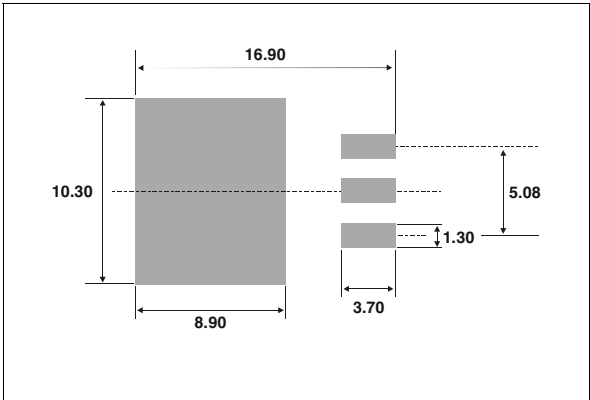
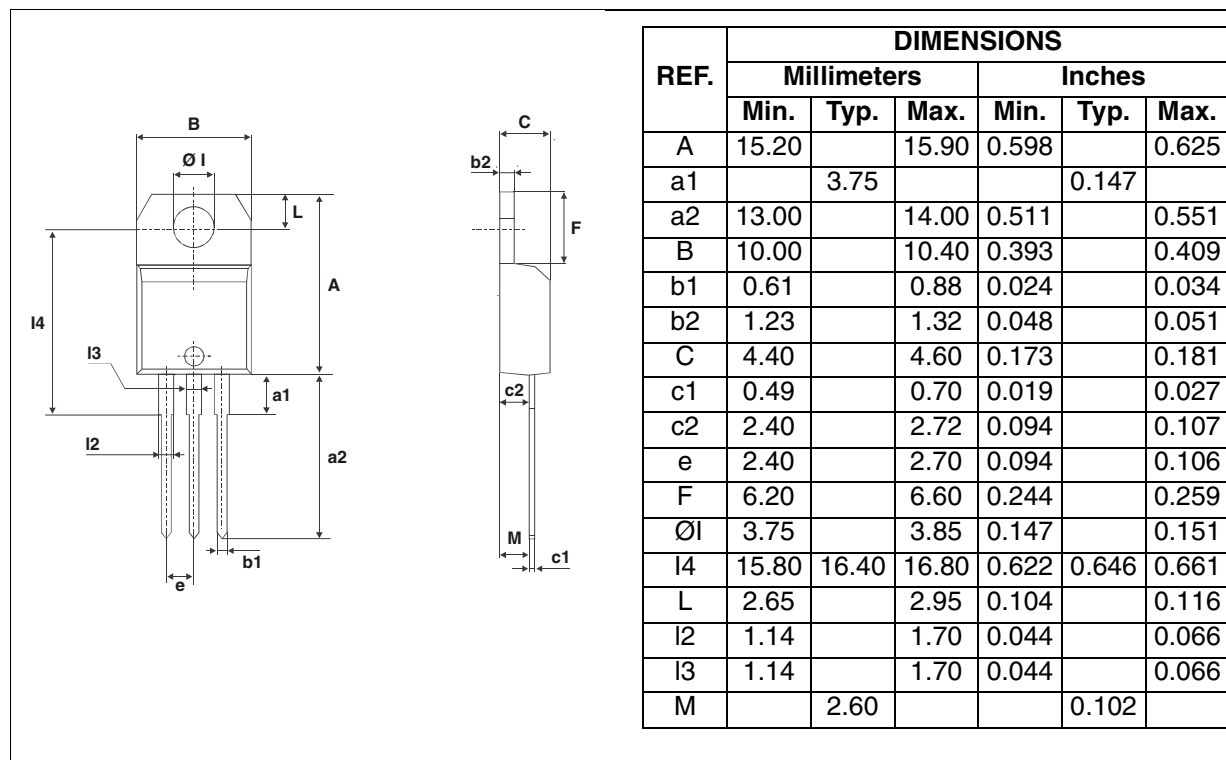


Figure 14: TO-220AB Package Mechanical Data


In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Table 7: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
TN2540-x00G	TN2540x00G	D ² PAK	1.5 g	50	Tube
TN2540-x00G-TR	TN2540x00G	D ² PAK	1.5 g	1000	Tape & reel
TYNx25RG	TYNx25	TO-220AB	2.3 g	50	Tube

Note: x = voltage

Table 8: Revision History

Date	Revision	Description of Changes
Apr-2002	4A	Last update.
13-Feb-2006	5	TO-220AB delivery mode changed from bulk to tube. ECOPACK statement added.

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